



PATENT  
2185-0570P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: Noriyuki ARAI et al. Conf.: 4527  
Appl. No.: 09/939,644 Group: 1712  
Filed: August 28, 2001 Examiner: P. A. Short  
For: THERMOPLASTIC RESIN COMPOSITION AND  
MOLDING THEREOF

RECEIVED  
AUG 30 2004  
TC 1700

SUPPLEMENTAL REPLY TO RESTRICTION REQUIREMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

August 23, 2004

Sir:

In reply to the Office Action dated May 26, 2004, the due date for responding having been extended two months to August 26, 2004, the following remarks supplemental to the Reply to the Restriction Requirement filed October 3, 2002 are respectfully submitted in connection with the above-identified application.

This reply includes: Remarks.